MC74VHCT32A

Product Preview
Quad 2-Input OR Gate / CMOS Logic Level Shifter
with LSTTL–Compatible Inputs

The MC74VHCT32A is an advanced high speed CMOS 2–input OR gate fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Schottky TTL while maintaining CMOS low power dissipation.
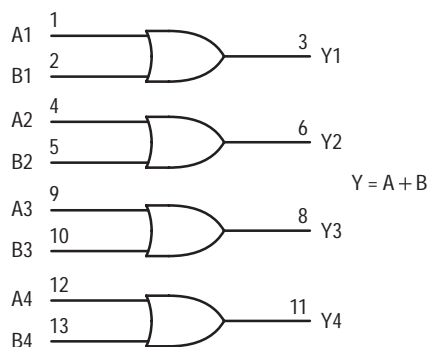
The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output.

The device input is compatible with TTL–type input thresholds and the output has a full 5V CMOS level output swing. The input protection circuitry on this device allows overvoltage tolerance on the input, allowing the device to be used as a logic–level translator from 3.0V CMOS logic to 5.0V CMOS Logic or from 1.8V CMOS logic to 3.0V CMOS Logic while operating at the high–voltage power supply.

The MC74VHCT32A input structure provides protection when voltages up to 7V are applied, regardless of the supply voltage. This allows the MC74VHCT32A to be used to interface 5V circuits to 3V circuits. The output structures also provide protection when $V_{CC} = 0V$. These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

- High Speed: t_{PD} = 3.8ns (Typ) at V_{CC} = 5V
- Low Power Dissipation: I_{CC} = 2µA (Max) at T_A = 25°C
- TTL–Compatible Inputs: V_{IL} = 0.8V; V_{IH} = 2.0V
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2V to 5.5V Operating Range
- Low Noise: V_{OLP} = 0.8V (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300mA
- ESD Performance: HBM > 2000V; Machine Model > 200V

14–LEAD SOIC
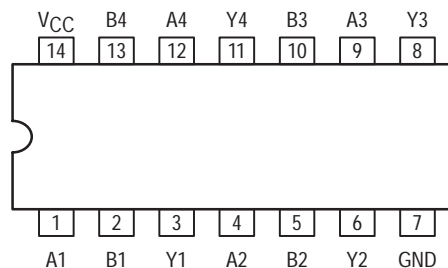**D SUFFIX**
CASE 751A

14–LEAD TSSOP
DT SUFFIX
CASE 948G
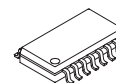
14–LEAD SOIC EIAJ
M SUFFIX
CASE 965

PIN CONNECTION AND
MARKING DIAGRAM (Top View)

For detailed package marking information, see the Marking Diagram section on page 4 of this data sheet.

FUNCTION TABLE

Inputs		Output
A	**B**	**Y**
L	L	L
L	H	H
H	L	H
H	H	H

ORDERING INFORMATION

Device	Package	Shipping
MC74VHCT32AD	SOIC	55 Units/Rail
MC74VHCT32ADT	TSSOP	96 Units/Rail
MC74VHCT32AM	SOIC EIAJ	50 Units/Rail

LOGIC DIAGRAM

$$Y = A + B$$

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

MC74VHCT32A

MAXIMUM RATINGS*

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		-0.5 to $+7.0$	V
V_{in}	DC Input Voltage		-0.5 to $+7.0$	V
V_{out}	DC Output Voltage	$V_{CC} = 0$ High or Low State	-0.5 to $+7.0$ -0.5 to $V_{CC} + 0.5$	V
I_{IK}	Input Diode Current		-20	mA
I_{OK}	Output Diode Current ($V_{OUT} <$ GND; $V_{OUT} > V_{CC}$)		± 20	mA
I_{out}	DC Output Current, per Pin		± 25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins		± 50	mA
P_D	Power Dissipation in Still Air, SOIC Packages† TSSOP Package†		500 450	mW
T_{stg}	Storage Temperature		-65 to $+150$	°C

* Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied.

†Derating — SOIC Packages: -7 mW/°C from 65° to 125°C
TSSOP Package: -6.1 mW/°C from 65° to 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND $\leq$ (V_{in} or V_{out}) $\leq V_{CC}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

RECOMMENDED OPERATING CONDITIONS

Characteristics		Symbol	Min	Max	Unit
DC Supply Voltage		V_{CC}	2.0	5.5	V
DC Input Voltage		V_{IN}	0.0	5.5	V
DC Output Voltage	$V_{CC} = 0$ High or Low State	V_{OUT}	0.0 0.0	5.5 V_{CC}	V
Operating Temperature Range		T_A	-55	$+85$	°C
Input Rise and Fall Time	$V_{CC} = 3.3V \pm 0.3V$ $V_{CC} = 5.0V \pm 0.5V$	t_r , t_f	0 0	100 20	ns/V

NOISE CHARACTERISTICS (Input t_r = t_f = 3.0ns, C_L = 50pF, V_{CC} = 5.0V)

Symbol	Characteristic	$T_A = 25$°C		Unit
		Typ	Max	
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	0.3	0.8	V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	-0.3	-0.8	V
V_{IHD}	Minimum High Level Dynamic Input Voltage		3.5	V
V_{ILD}	Maximum Low Level Dynamic Input Voltage		1.5	V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} (V)	$T_A = 25°C$ Min	Typ	Max	$T_A \leq 85°C$ Min	Max	$T_A \leq 125°C$ Min	Max	Unit
V_{IH}	Minimum High–Level Input Voltage		3.0 4.5 5.5	1.2 2.0 2.0			1.2 2.0 2.0		1.2 2.0 2.0		V
V_{IL}	Maximum Low–Level Input Voltage		3.0 4.5 5.5			0.53 0.8 0.8		0.53 0.8 0.8		0.53 0.8 0.8	V
V_{OH}	Minimum High–Level Output Voltage $V_{IN} = V_{IH}$ or V_{IL}	$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -50\mu A$	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -4mA$ $I_{OH} = -8mA$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V_{OL}	Maximum Low–Level Output Voltage $V_{IN} = V_{IH}$ or V_{IL}	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 50\mu A$	3.0 4.5		0.0 0.0	0.1 0.1		0.1 0.1		0.1 0.1	V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 4mA$ $I_{OL} = 8mA$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	V
I_{IN}	Maximum Input Leakage Current	$V_{IN} = 5.5V$ or GND	0 to 5.5			±0.1		±1.0		±1.0	µA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			2.0		20		40	µA
I_{CCT}	Quiescent Supply Current	Input: $V_{IN} = 3.4V$	5.5			1.35		1.50		1.65	mA
I_{OPD}	Output Leakage Current	$V_{OUT} = 5.5V$	0.0			0.5		5.0		10	µA

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0ns$)

Symbol	Parameter	Test Conditions	$T_A = 25°C$ Min	Typ	Max	$T_A = -40$ to $85°C$ Min	Max	Unit
t_{PLH}, t_{PHL}	Maximum Propagation Delay, A or B to Y	$V_{CC} = 3.3 \pm 0.3V$ $C_L = 15pF$ $C_L = 50pF$		5.5 8.0	7.9 11.4	1.0 1.0	9.5 13.0	ns
		$V_{CC} = 5.0 \pm 0.5V$ $C_L = 15pF$ $C_L = 50pF$		3.8 5.3	5.5 7.5	1.0 1.0	6.5 8.5	
C_{in}	Maximum Input Capacitance			4	10		10	pF

		Typical @ 25°C, $V_{CC} = 5.0V$	
C_{PD}	Power Dissipation Capacitance (Note 1.)	22	pF

1. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}/4$ (per gate). C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.
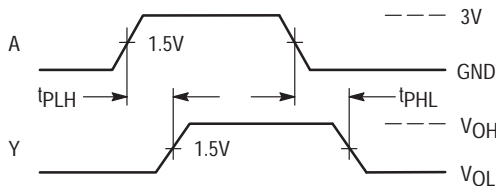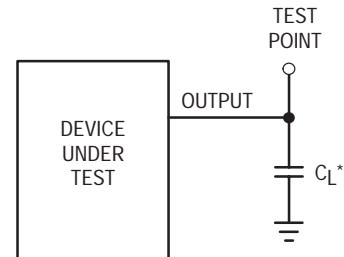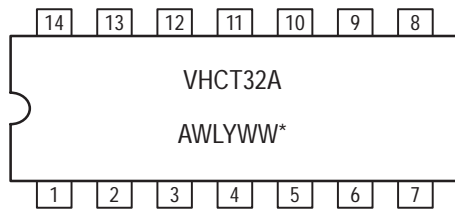

Figure 1. Switching Waveforms
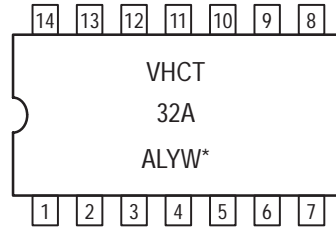

*Includes all probe and jig capacitance
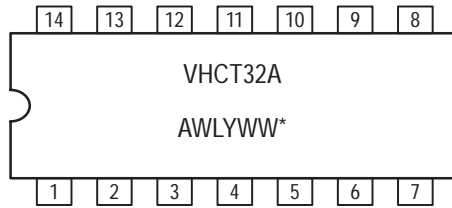
Figure 2. Test Circuit

MC74VHCT32A

MARKING DIAGRAMS
(Top View)

14–LEAD SOIC
D SUFFIX
CASE 751A

VHCT32A

AWLYWW*

14–LEAD TSSOP
DT SUFFIX
CASE 948G

VHCT

32A

ALYW*

14–LEAD SOIC EIAJ
M SUFFIX
CASE 965

VHCT32A

AWLYWW*

*See Applications Note #AND8004/D for date code and traceability information.

PACKAGE DIMENSIONS
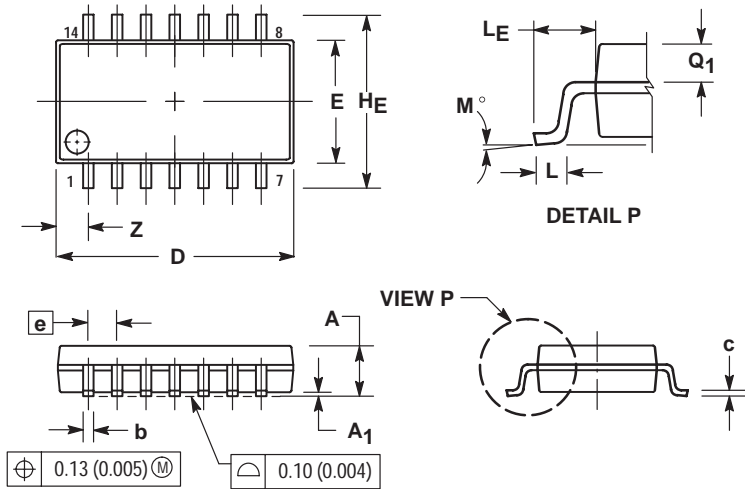
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751A–03
ISSUE F
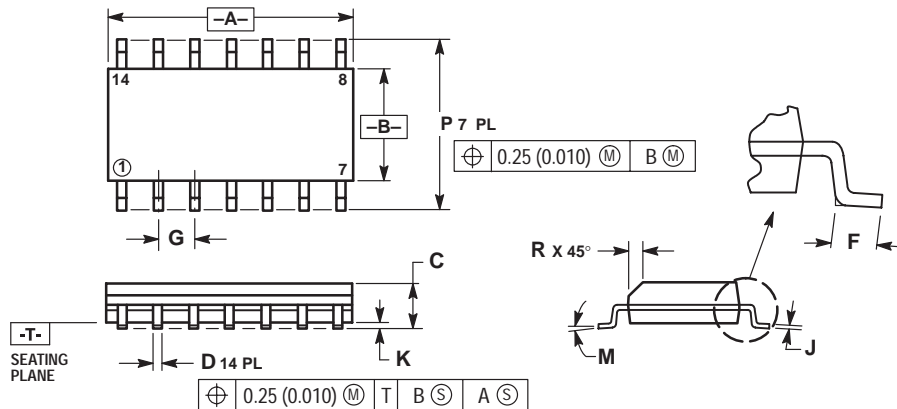
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948G–01
ISSUE O

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	–––	1.20	–––	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

MC74VHCT32A

PACKAGE DIMENSIONS

M SUFFIX
PLASTIC SOIC EIAJ PACKAGE
CASE 965–01
ISSUE O

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	–––	2.05	–––	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	–––	1.42	–––	0.056

DETAIL P

VIEW P

| ⊕ | 0.13 (0.005) Ⓜ |

| △ | 0.10 (0.004) |

Notes

PUBLICATION ORDERING INFORMATION